

SN# 377286

POSITIONING FLOWABLE SOLDER FOR
BONDING INTEGRATED CIRCUIT ELEMENTS

Abstract of the Disclosure

5 A solder mask defined bond pad or a non-solder mask
defined bond pad may be configured to center the solder
over the bond pad using either surface attractive forces or
capillary action. In some embodiments, a stub trace may be
provided, for example, in opposition to the real trace to
provide a capillary counter-attractive force on the solder.
In other embodiments, the surface attractive action of the
edge of the solder mask may be utilized to center the
10 solder. In still other embodiments, the natural attractive
force of a trace on solder may be utilized to appropriately
position solder where desired, for example, to line up with
other solder deposits.